

# SN5473, SN54LS73A, SN7473, SN74LS73A DUAL J-K FLIP-FLOPS WITH CLEAR

SDLS118 – DECEMBER 1983 – REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

## description

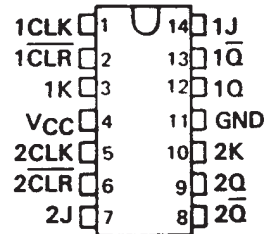
The '73, and 'H73, contain two independent J-K flip-flops with individual J-K, clock, and direct clear inputs. The '73, and 'H73, are positive pulse-triggered flip-flops. J-K input is loaded into the master while the clock is high and transferred to the slave on the high-to-low transition. For these devices the J and K inputs must be stable while the clock is high.

The 'LS73A contains two independent negative-edge-triggered flip-flops. The J and K inputs must be stable one setup time prior to the high-to-low clock transition for predictable operation. When the clear is low, it overrides the clock and data inputs forcing the Q output low and the  $\bar{Q}$  output high.

The SN5473, SN54H73, and the SN54LS73A are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN7473, and the SN74LS73A are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN5473, SN54LS73A . . . J OR W PACKAGE  
SN7473 . . . N PACKAGE  
SN74LS73A . . . D OR N PACKAGE

(TOP VIEW)



73  
FUNCTION TABLE

INPUTS				OUTPUTS	
CLR	CLK	J	K	Q	$\bar{Q}$
L	X	X	X	L	H
H		L	L	$Q_0$	$\bar{Q}_0$
H		H	L	H	L
H		L	H	L	H
H		H	H	TOGGLE	TOGGLE

'LS73A  
FUNCTION TABLE

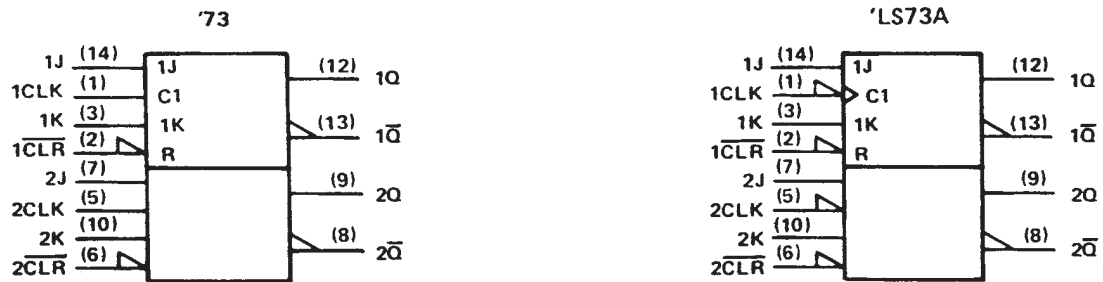
INPUTS				OUTPUTS	
CLR	CLK	J	K	Q	$\bar{Q}$
L	X	X	X	L	H
H	$\downarrow$	L	L	$Q_0$	$\bar{Q}_0$
H	$\downarrow$	H	L	H	L
H	$\downarrow$	L	H	L	H
H	$\downarrow$	H	H	TOGGLE	TOGGLE
H	H	X	X	$Q_0$	$\bar{Q}_0$

FOR CHIP CARRIER INFORMATION,  
CONTACT THE FACTORY

# SN5473, SN54LS73A, SN7473, SN74LS73A DUAL J-K FLIP-FLOPS WITH CLEAR

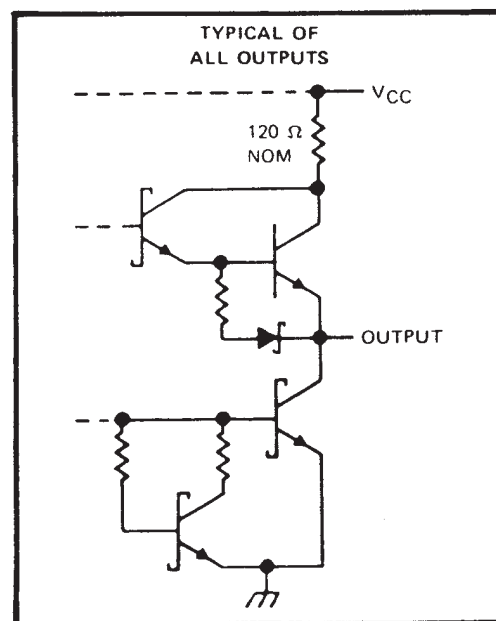
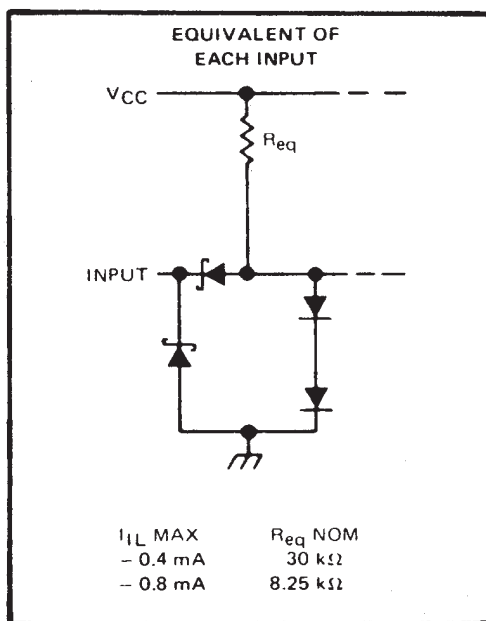
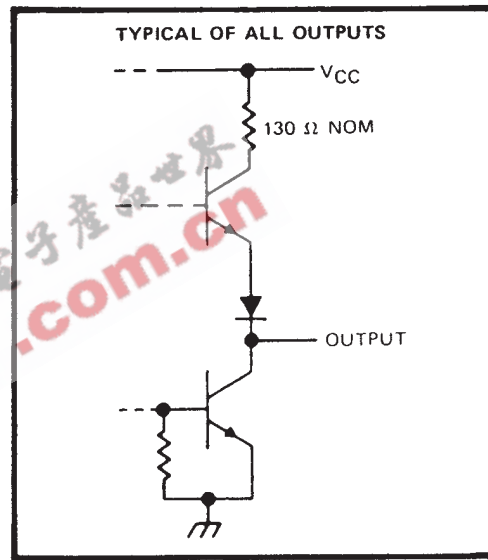
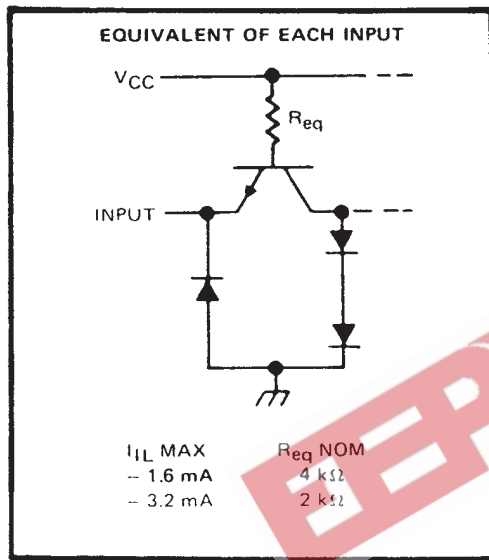
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## logic symbols†



†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

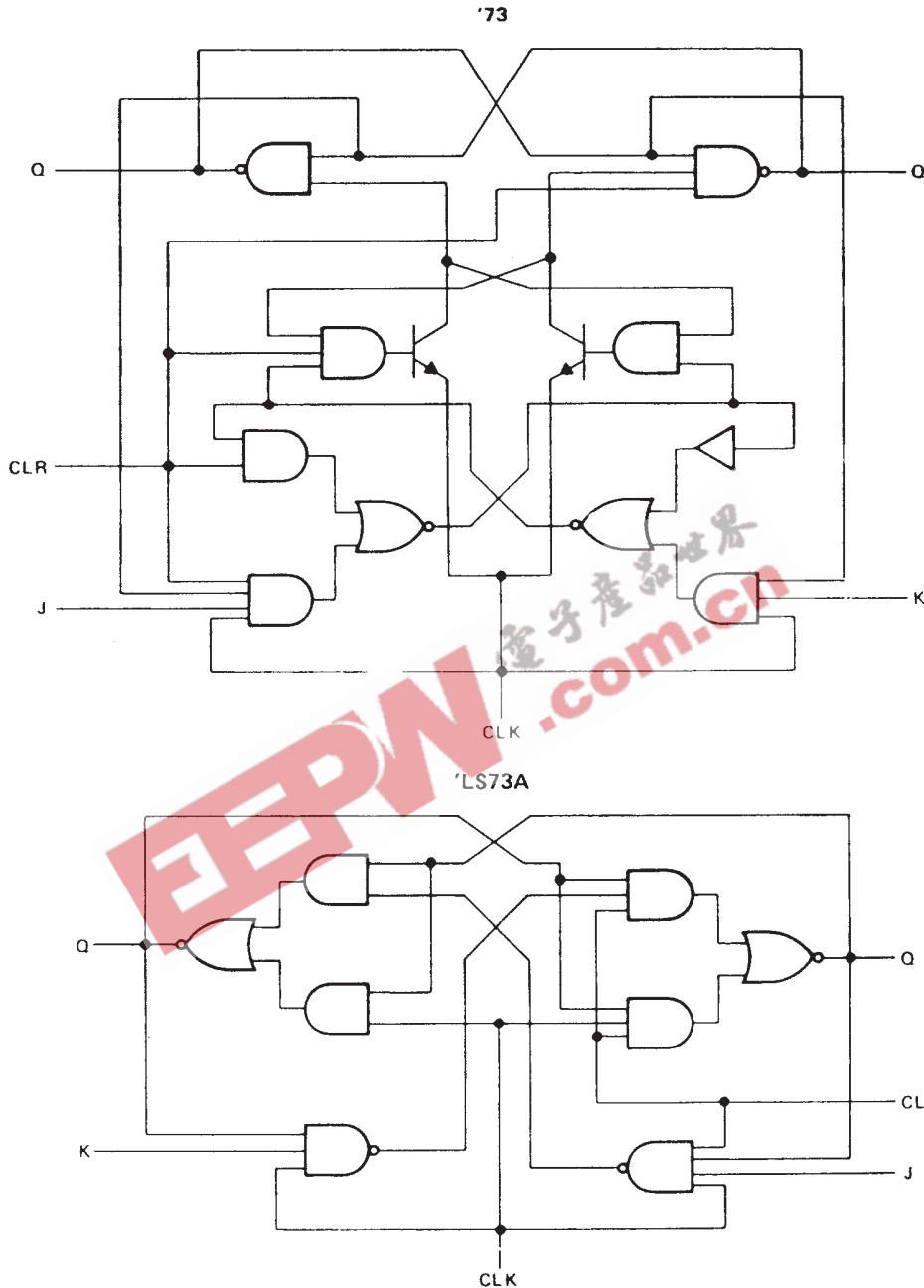
## schematics of inputs and outputs



# SN5473, SN54LS73A, SN7473, SN74LS73A DUAL J-K FLIP-FLOPS WITH CLEAR

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## logic diagrams (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (See Note 1) .....	7 V
Input voltage: '73 .....	5.5 V
'LS73A .....	7 V
Operating free-air temperature range: SN54' .....	-55°C to 125°C
SN74' .....	0°C to 70°C
Storage temperature range .....	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



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# SN5473, SN54LS73A, SN7473, SN74LS73A DUAL J-K FLIP-FLOPS WITH CLEAR

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## recommended operating conditions

	SN5473			SN7473			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$ Supply voltage	4.5	5	5.5	4.75	5	5.25	V
$V_{IH}$ High-level input voltage	2			2			V
$V_{IL}$ Low-level input voltage			0.8			0.8	V
$I_{OH}$ High-level output current			-0.4			-0.4	mA
$I_{OL}$ Low-level output current			16			16	mA
$t_w$ Pulse duration	CLK high	20		20			ns
	CLK low	47		47			
	$\overline{CLR}$ low	25		25			
$t_{su}$ Input setup time before CLK $\uparrow$	0			0			ns
$t_h$ Input hold time data after CLK $\downarrow$	0			0			ns
$T_A$ Operating free-air temperature	-55		125	0		70	$^{\circ}C$

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS <sup>†</sup>	SN5473			SN7473			UNIT
		MIN	TYP <sup>‡</sup>	MAX	MIN	TYP <sup>‡</sup>	MAX	
$V_{IK}$	$V_{CC} = \text{MIN}, I_I = -12 \text{ mA}$			-1.5			-1.5	V
$V_{OH}$	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OH} = -0.4 \text{ mA}$	2.4	3.4		2.4	3.4		V
$V_{OL}$	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 16 \text{ mA}$		0.2	0.4		0.2	0.4	V
$I_I$	$V_{CC} = \text{MAX}, V_I = 5.5 \text{ V}$			1			1	mA
$I_{IH}$	J or K			40			40	$\mu\text{A}$
	$\overline{CLR}$ or CLK			80			80	
$I_{IL}$	J or K			-1.6			-1.6	mA
	$\overline{CLR}$			-3.2			-3.2	
	CLK			-3.2			-3.2	
$I_{OS}$ <sup>§</sup>	$V_{CC} = \text{MAX}$	-20		-57	-18		-57	mA
$I_{CC}$ <sup>¶</sup>	$V_{CC} = \text{MAX},$ See Note 2		10	20		10	20	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}C$ .

<sup>§</sup> Not more than one output should be shorted at a time.

<sup>¶</sup> Average per flip-flop.

NOTE 2: With all outputs open,  $I_{CC}$  is measured with the Q and  $\overline{Q}$  outputs high in turn. At the time of measurement, the clock input is grounded.

## switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}C$ (see note 3)

PARAMETER <sup>#</sup>	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$f_{max}$				15	20		MHz
$t_{PLH}$	$\overline{CLR}$	$\overline{Q}$	$R_L = 400 \Omega, C_L = 15 \text{ pF}$		16	25	ns
$t_{PHL}$		Q			25	40	ns
$t_{PLH}$	CLK	Q or $\overline{Q}$			16	25	ns
$t_{PHL}$					25	40	ns

<sup>#</sup> $f_{max}$  = maximum clock frequency;  $t_{PLH}$  = propagation delay time, low-to-high-level output;  $t_{PHL}$  = propagation delay time, high-to-low-level output.

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

# SN5473, SN54LS73A, SN7473, SN74LS73A DUAL J-K FLIP-FLOPS WITH CLEAR

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## recommended operating conditions

		SN54LS73A			SN74LS73A			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX		
$V_{CC}$	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
$V_{IH}$	High-level input voltage	2			2			V	
$V_{IL}$	Low-level input voltage			0.7			0.8	V	
$I_{OH}$	High-level output current			-0.4			-0.4	mA	
$I_{OL}$	Low-level output current			4			8	mA	
$f_{clock}$	Clock frequency	0		30	0		30	MHz	
$t_w$	Pulse duration	CLK high		20	20			ns	
		CLR low		25	20				
$t_{su}$	Set up time-before CLK ↓	data high or low		20	20			ns	
		CLR inactive		20	20				
$t_h$	Hold time-data after CLK ↓	0		0				ns	
$T_A$	Operating free-air temperature	-55		125		0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS73A		SN74LS73A		UNIT
		MIN	TYP‡	MAX	MIN	
$V_{IK}$	$V_{CC} = \text{MIN}$ , $I_I = -18 \text{ mA}$	-1.5		-1.5		V
$V_{OH}$	$V_{CC} = \text{MIN}$ , $V_{IH} = 2 \text{ V}$ , $V_{IL} = \text{MAX}$ , $I_{OH} = -0.4 \text{ mA}$	2.5	3.4	2.7	3.4	V
$V_{OL}$	$V_{CC} = \text{MIN}$ , $V_{IL} = \text{MAX}$ , $V_{IH} = 2 \text{ V}$ , $I_{OL} = 4 \text{ mA}$	0.25		0.4		V
	$V_{CC} = \text{MIN}$ , $V_{IL} = \text{MAX}$ , $V_{IH} = 2 \text{ V}$ , $I_{OL} = 8 \text{ mA}$			0.35		
$I_I$	J or K			0.1		mA
	CLR			0.3		
	CLK			0.4		
$I_{IH}$	J or K			20		μA
	CLR			60		
	CLK			80		
$I_{IL}$	J or K			-0.4		mA
	CLR or CLK			-0.8		
$I_{OS}§$	$V_{CC} = \text{MAX}$ , See Note 4	-20	-100	-20	-100	mA
$I_{CC} \text{ (Total)}$	$V_{CC} = \text{MAX}$ , See Note 2	4		6		mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open,  $I_{CC}$  is measured with the Q and  $\bar{Q}$  outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with  $V_O = 2.25 \text{ V}$  and  $2.125 \text{ V}$  for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^\circ\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
$f_{max}$				30	45		MHz	
$t_{PLH}$	CLR or CLK	Q or $\bar{Q}$	$R_L = 2 \text{ k}\Omega$ , $C_L = 15 \text{ pF}$			15	20	ns
$t_{PHL}$						15	20	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9675101QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9675101QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9675101QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9675101VCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9675101VCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9675101VDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9675101VDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS73AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS73AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN7473N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7473N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7473N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7473N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS73AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS73AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS73AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS73ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS73ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SNJ54LS73AFD	OBSOLETE	LCCC	FK	20		TBD	Call TI	Level-NC-NC-NC
SNJ54LS73AFD	OBSOLETE	LCCC	FK	20		TBD	Call TI	Level-NC-NC-NC
SNJ54LS73AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS73AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS73AW	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS73AW	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

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**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

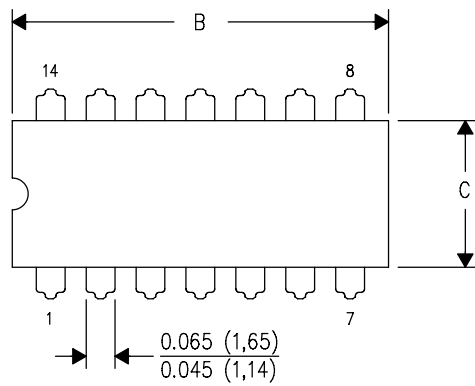
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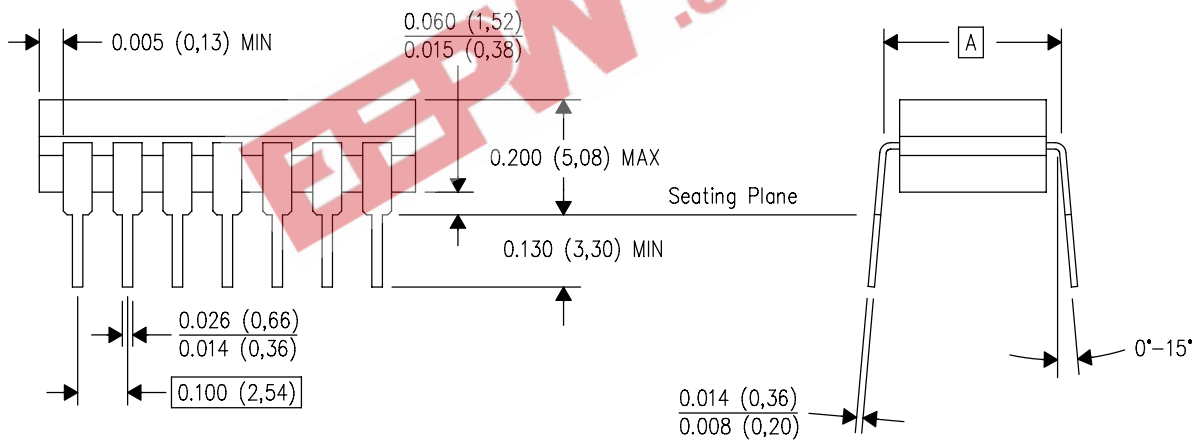
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J (R-GDIP-T\*\*)  
14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



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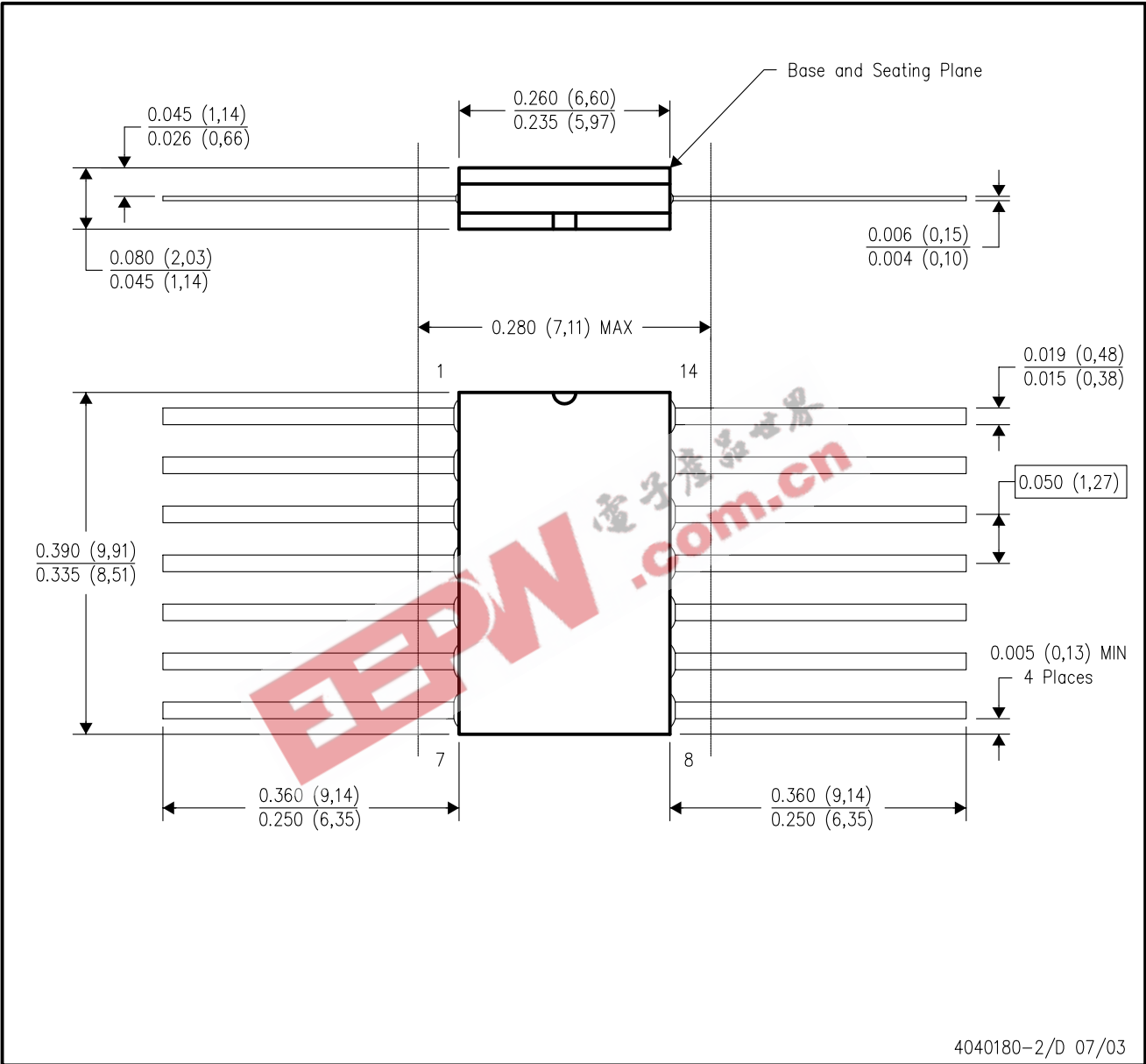
- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



MECHANICAL DATA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

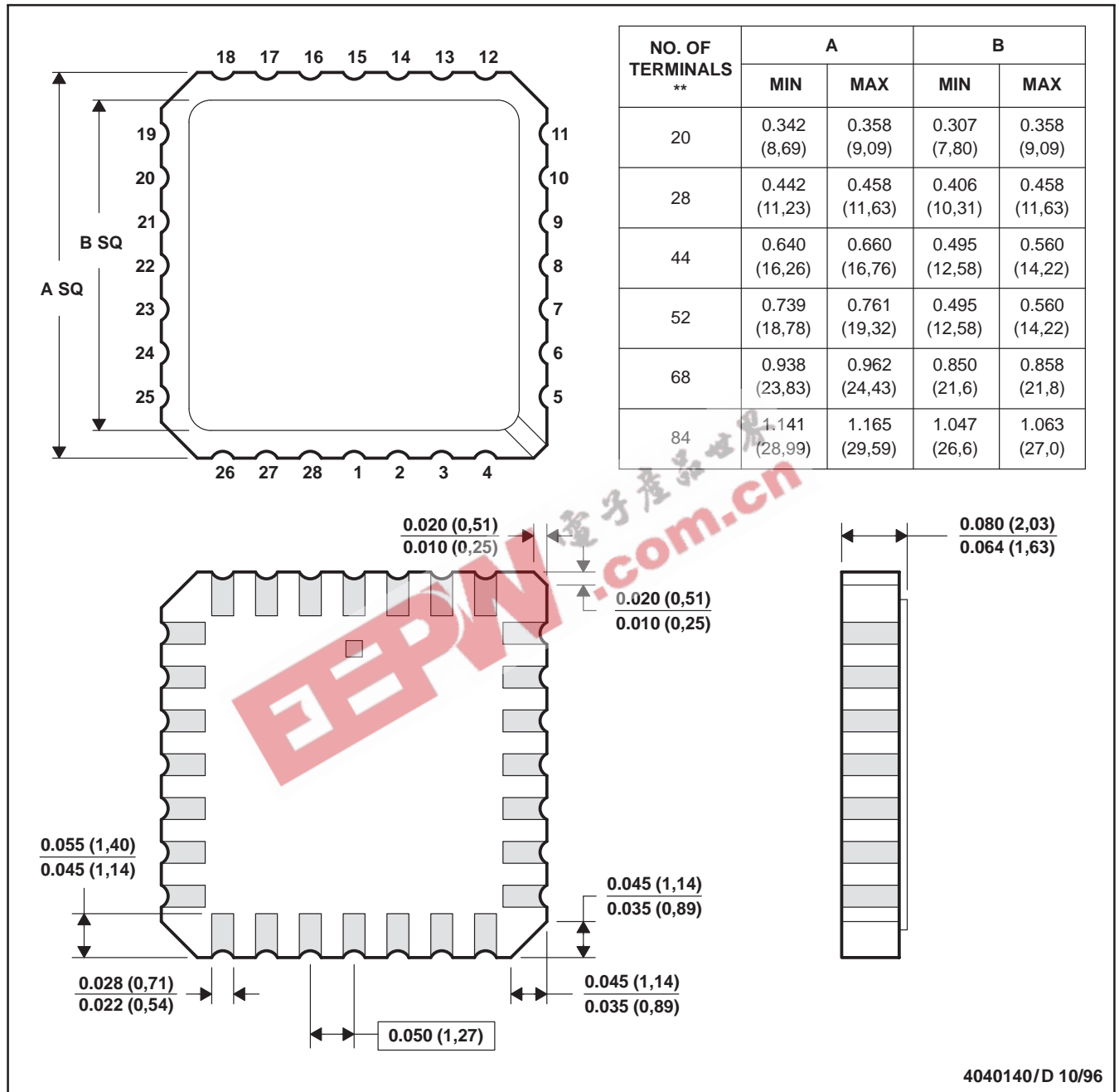


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



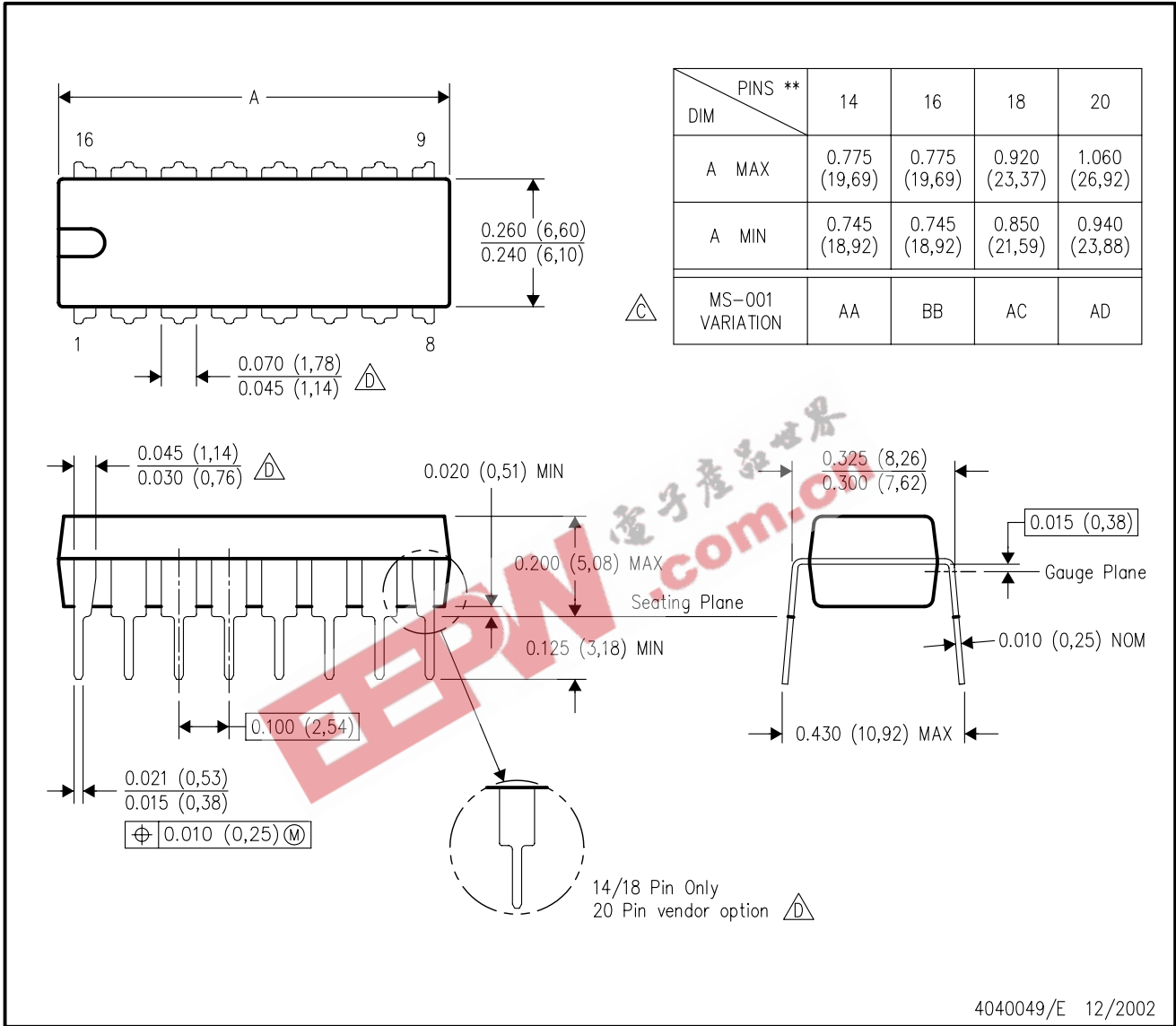
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

# MECHANICAL DATA

## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



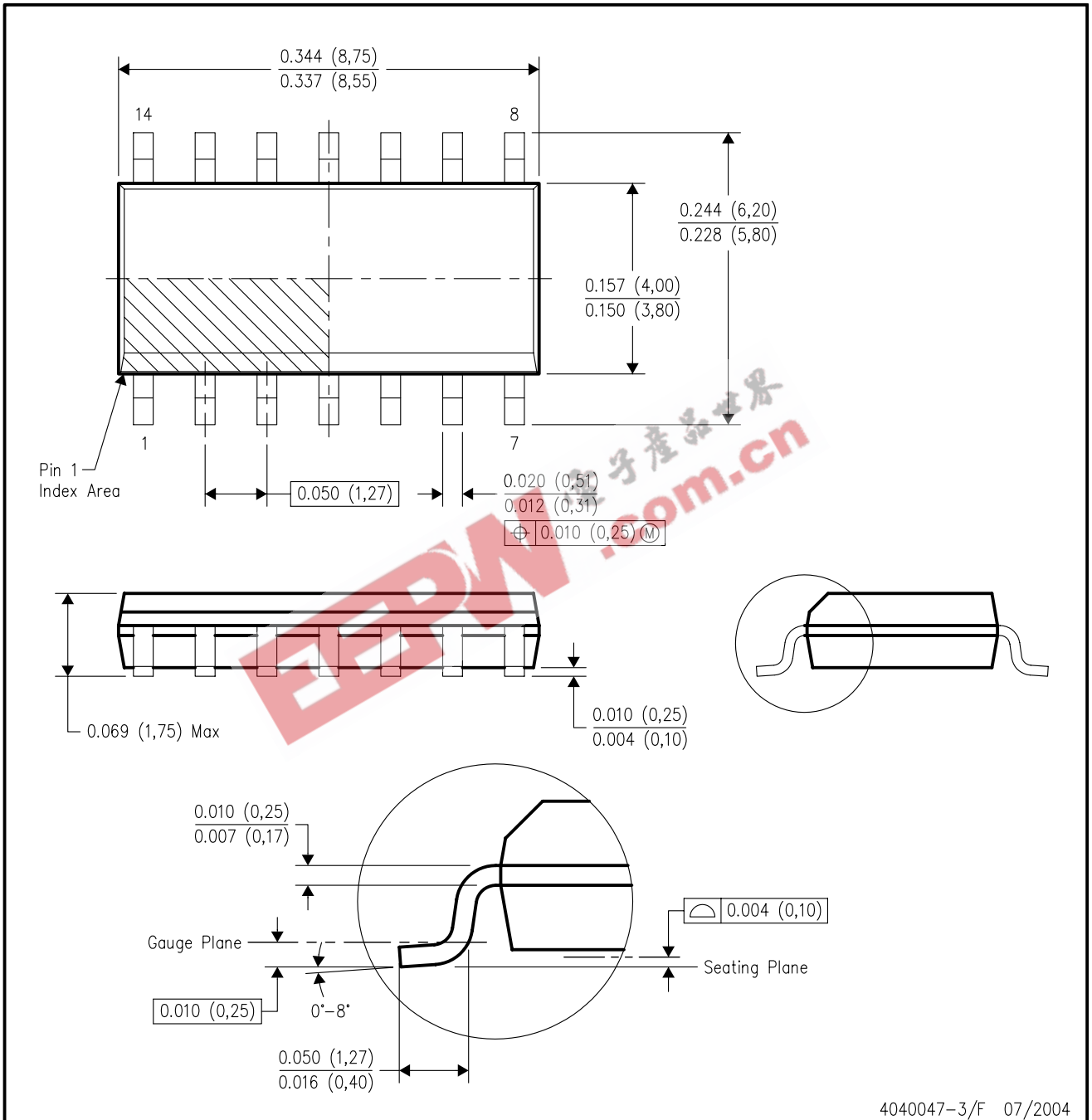
4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

# MECHANICAL DATA

## D (R-PDSO-G14)

## PLASTIC SMALL-OUTLINE PACKAGE



4040047-3/F 07/2004

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MS-012 variation AB.

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DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>	Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
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